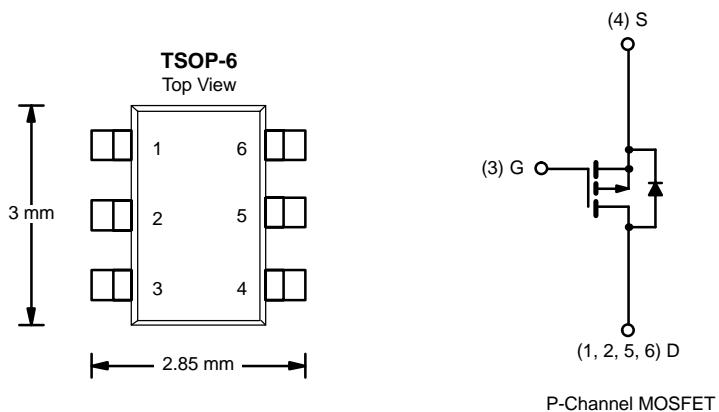


P-Channel 1.8-V (G-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-12	0.050 @ $V_{GS} = -4.5$ V	± 5.2
	0.070 @ $V_{GS} = -2.5$ V	± 4.4
	0.095 @ $V_{GS} = -1.8$ V	± 3.8

TrenchFET®
Power MOSFETs
1.8-V Rated



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	-12	V	
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^{a, b}	I_D	± 5.2	A	
		± 4.1		
Pulsed Drain Current	I_{DM}	± 20		
Continuous Source Current (Diode Conduction) ^{a, b}	I_S	-1.7		
Maximum Power Dissipation ^{a, b}	P_D	2.0	W	
		1.3		
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}		62.5		°C/W
		106			

Notes

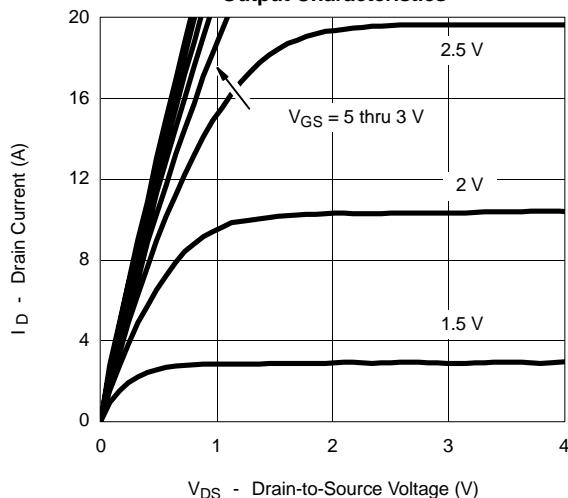
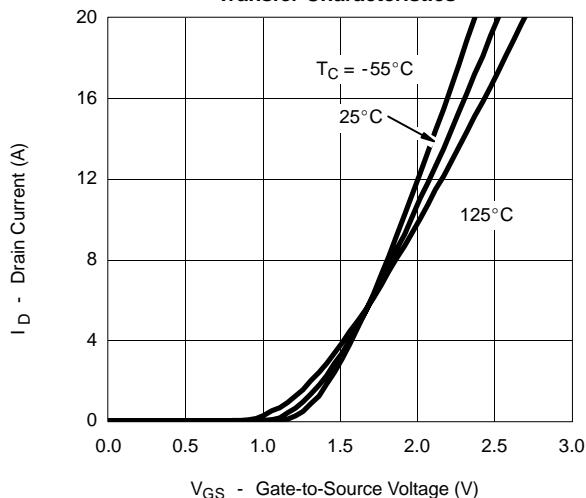
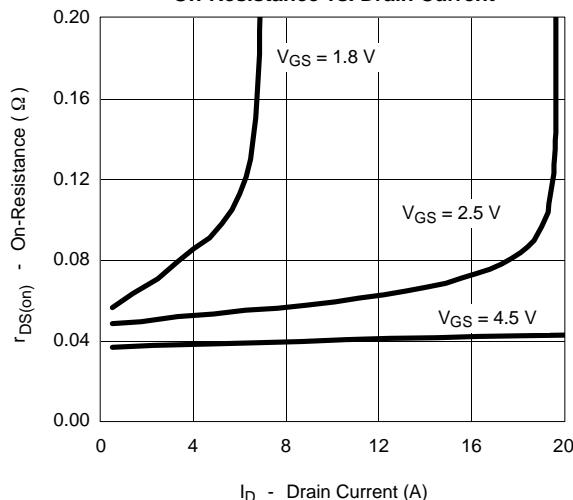
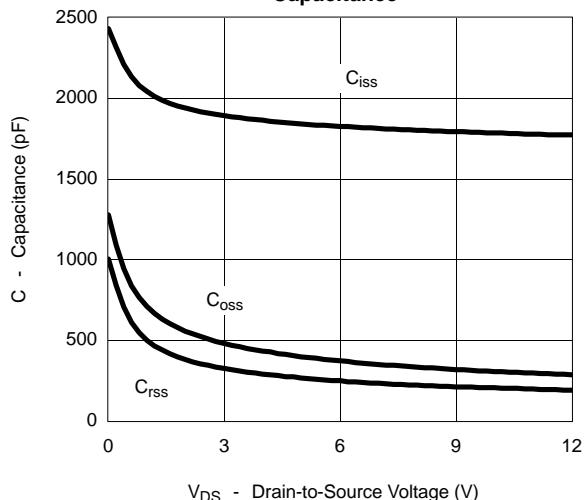
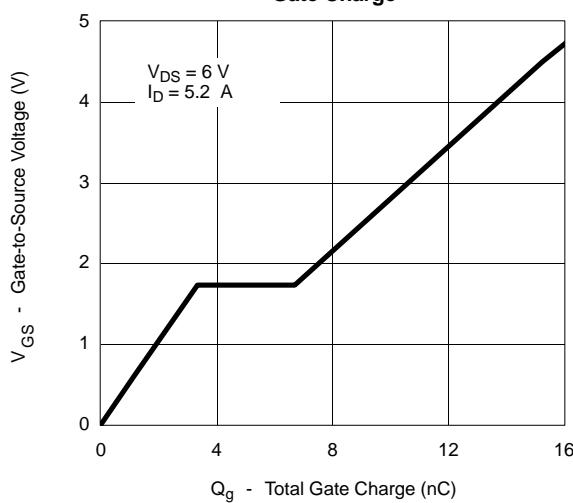
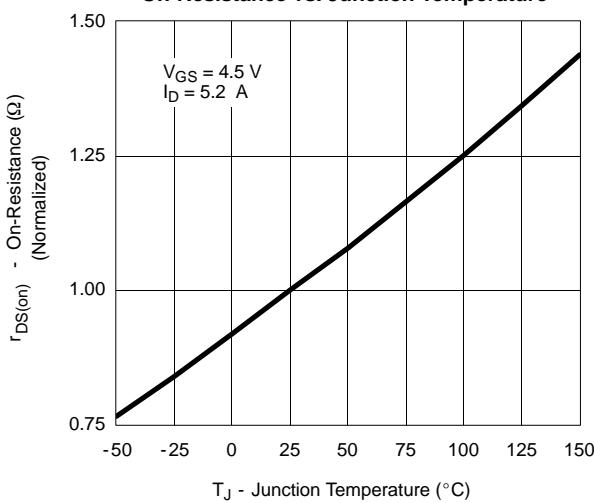
- a. Surface Mounted on FR4 Board.
- b. $t \leq 5$ sec.

SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-0.45			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -9.6 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μA
		$V_{DS} = -9.6 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 70^\circ\text{C}$			-5	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-15			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = -4.5 \text{ V}, I_D = -5.2 \text{ A}$		0.040	0.050	Ω
		$V_{GS} = -2.5 \text{ V}, I_D = -4.4 \text{ A}$		0.056	0.070	
		$V_{GS} = -1.8 \text{ V}, I_D = -2.0 \text{ A}$		0.072	0.095	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10 \text{ V}, I_D = -5.2 \text{ A}$		15		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -1.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -5.2 \text{ A}$		16	25	nC
Gate-Source Charge	Q_{gs}			3.5		
Gate-Drain Charge	Q_{gd}			2.5		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -6 \text{ V}, R_L = 10 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_G = 6 \Omega$		20	40	ns
Rise Time	t_r			45	90	
Turn-Off Delay Time	$t_{d(\text{off})}$			100	200	
Fall Time	t_f			75	150	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -1.7 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		60	100	

Notes

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
